

## SCOPE OF ACCREDITATION

### Electronics - Printed Boards

**Eltek Ltd**  
Galis 20 Street  
Petach-Tikva, 49101  
Israel

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: [www.eAuditNet.com](http://www.eAuditNet.com) - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

#### **AC7000 Rev A - AUDIT CRITERIA FOR NADCAP ACCREDITATION**

##### **AC7119 Rev K - Nadcap Audit Criteria for Electronics Printed Boards (to be used on audits BEFORE 22-Feb-2026)**

Engineering Source File Processing

Final Validation

General Printed Boards (Select if no other options apply)

##### **AC7119/2 Rev C - Nadcap Audit Criteria for Electronics Flexible and Rigid-Flexible Printed Boards (to be used on audits on/AFTER 05-Nov-2023)**

General Flexible and Rigid-Flexible Printed Boards (Select if no other options apply)

Stiffener Bonding

Strain Relief

##### **AC7119/5 Rev A - Nadcap Audit Criteria for Electronics High Frequency (MICROWAVE) Printed Boards (to be used on audits on/AFTER 31-Dec-2023)**

General High Frequency (Microwave) Printed Boards (Select if no other options apply)

##### **AC7119/6 Rev A - Nadcap Audit Criteria for In House Fabrication of Printed Boards (to be used on audits BEFORE 22-Feb-2026)**

General In House Fabrication of Printed Boards (Select if no other options apply)

Legend And Marking

Monthly Quality Conformance Testing

Permanent Solder Mask Application

Routing And Machining

Solder Mask Exposing

##### **AC7119/7 Rev NA - Nadcap Audit Criteria for Final Finishes and X-Ray Fluorescence (to be**

**used on audits BEFORE 22-Feb-2026)**

Electrodeposited Gold ASTM B-488  
Electroless Nickel Immersion Gold (ENIG) IPC-4552  
Hot Air Solder Leveling (HASL)/Solder J-STD-006  
Immersion Silver (IAg) IPC-4553  
Wire Bondable Plating  
X-Ray Fluorescence (XRF)

**AC7119/8 Rev NA - Nadcap Audit Criteria for Drilling (Mechanical & Laser) Printed Boards (to be used on audits on/AFTER 30-Jul-2023)**

General Drilling Printed Boards (select if no other options apply)  
Laser Drilling – In House

**AC7119/9 Rev NA - Nadcap Audit Criteria for Electrical Testing Printed Boards (to be used on audits on/AFTER 30-Jul-2023)**

Electrical Test

**AC7119/10 Rev A - Nadcap Audit Criteria for In House Fabrication of Printed Boards Via Fill & Planarization (to be used on audits on/AFTER 10-Nov-2024)**

Epoxy Hole Fill Non-Conductive And / Or Conductive  
Planarization

**AC7119/10 Rev A - Nadcap Audit Criteria for In House Fabrication of Printed Boards Via Fill & Planarization (to be used on audits on/AFTER 10-NOV-2024)**

**AC7119/11 Rev NA - Nadcap Audit Criteria for IPC-6012 & IPC-6018 Space and Military Avionics Applications Addendum (SMA) (to be used on/AFTER 08-Dec-2024)**